

TH 930

Silicone Thermal Putty

Description

TH 930 is a one-part thermal conductive interface material based on silicone resins. It does not bleed and flow. It is designed for very good thermal conduction with high electrical insulation.

Applications

1. Thermal conductive interface material for electronic parts and devices.

Guidelines for Use

1. Thaw the silicone to room temperature before use
2. Wear rubber glove when handling the silicone putty
3. Scoop a quantity of the silicone putty from the container using a stainless steel spoon
4. Work and knead the putty around electronic part and circuit by hand
5. Wipe off any excess party with a piece of dry cloth. Further cleaning of residues may be achieved by wiping with cloth wetted with isopropanol

Properties

Property	Test Method	Unit	Typical Value
Chemical type	-	-	Silicone
Appearance	Pen 10	-	White Putty
Mix ratio, by weight		-	1 component
Shelf life	Pen 26	Month	6
Viscosity, Brookfield RVT, 25°C	Pen 11	cP	Putty
Specific gravity, 25°C	Pen 14	-	3.2
Thermal Conductivity	ISO/DIS 22007	W/mK	4.3
Hardness	Pen 29	Shore 00	50

Storage

Tightly close original container of unused product and store in dark and cool place.

Packaging & Dimension

- 500g jar

Environment, Health & Safety

This product is RoHS compliant. It does not contain any known carcinogenic, mutagenic or teratogenic components.

Contact Information

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